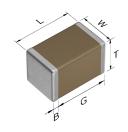
积层贴片陶瓷片式电容器

C2012X6S1C685M125AC

RoHS Reach Halogen Free Pb Free

交货型号	C2012X6S1C685MT****
用途	一般等级
特点	General 一般(~75V)
系列	C2012 [EIA 0805]
状态	▲ 量产体制(新设计非推荐)



尺寸		
长度(L)	2.00mm ±0.20mm	
宽度(W)	1.25mm ±0.20mm	
厚度(T)	1.25mm ±0.20mm	
端子宽度(B)	0.20mm Min.	
端子间隔(G)	0.50mm Min.	
推荐焊盘布局(PA)	1.00mm to 1.30mm(Flow Soldering)	
J世行。序盆作/四(t n)	0.90mm to 1.20mm(Reflow Soldering)	
推荐焊盘布局(PB)	1.00mm to 1.20mm(Flow Soldering)	
J世行。拜益州/四(t D)	0.70mm to 0.90mm (Reflow Soldering)	
推荐焊盘布局(PC)	0.80mm to 1.10mm(Flow Soldering)	
]此行/开血。印/四 (t C/	0.90mm to 1.20mm(Reflow Soldering)	

电气特性		
电容	6.8 μ F ±20%	
额定电压	16VDC	
温度特性	X6S (±22%)	
耗散因数(Max.)	10%	
绝缘电阻 (Min.)	14ΜΩ	

	其他
焊接方法	流体
/	回流
AEC-Q200	NO NO
包装形式	塑封编带 (180mm卷筒)
包装个数	2000pcs

[!] Images are for reference only and show exemplary products.

[!] This PDF document was created based on the data listed on the TDK Corporation website.

[!] All specifications are subject to change without notice.

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特性图表(这是参考数据,并不保证产品的特性。)

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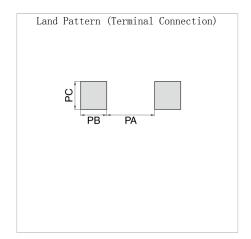
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Associated Images



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